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(71) Applicant (for all designated States except US): **EBARA CORPORATION** [JP/JP]; 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, 1448510 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **HIROKAWA, Kazuto** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, 1448510 (JP). **TSUJIMURA, Manabu** [JP/JP]; c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, 1448510 (JP).

(74) Agents: **WATANABE, Isamu** et al.; Gowa Nishi-Shinjuku 4F 5-8, Nishi-Shinjuku 7-chome, Shinjuku-ku, Tokyo, 1600023 (JP).

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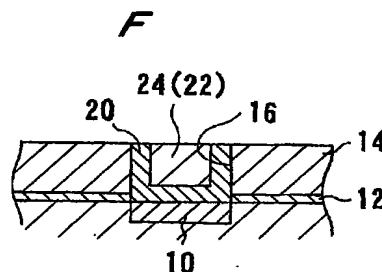
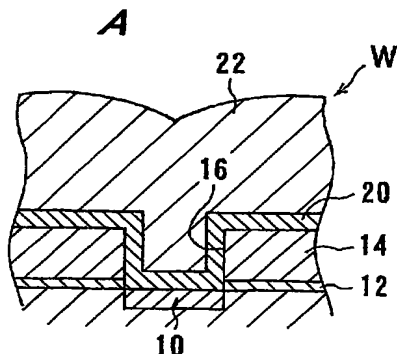
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(54) Title: SUBSTRATE PROCESSING METHOD AND SUBSTRATE PROCESSING APPARATUS



(57) Abstract: The present invention provides a substrate processing method that can perform improved flattening and processing upon the formation of interconnects. The a substrate processing method includes a step of eliminating a level difference in a surface of a interconnect material to flatten a surface, a step of removing the interconnect material until the interconnect material present in the non-interconnect region of the substrate becomes a thin film or remains partly on a barrier material, a step of removing the interconnect material in the form of the thin film or remaining partly on the barrier material, a step of simultaneously removing the unnecessary interconnect material and the barrier material until the barrier material present in the non-interconnect region becomes a thin film or remains partly, and a step of removing the unnecessary interconnect material and the barrier material in the form of the thin film.

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